WHAT IS CLAIMED IS:

1. An apparatus comprising:

an integrated circuit die;

an integrated circuit package coupled to the integrated circuit die;

mold compound in contact with the integrated circuit die and the integrated circuit package; and

an interconnect coupled to the integrated circuit package,

wherein a first portion of the interconnect is in contact with the mold compound, wherein a second portion of the interconnect is not in contact with the mold compound, and wherein a third portion of the interconnect is in contact with the integrated circuit package.

2. An apparatus according to Claim 1, wherein the second portion is an upper portion of the interconnect and the third portion is a lower portion of the interconnect.

3. An apparatus according to Claim 1, further comprising:

a second integrated circuit package;

a second interconnect coupled to the second integrated circuit package,

wherein the second interconnect is coupled to the first interconnect.

4. An apparatus according to Claim 3, wherein the second integrated circuit package is coupled to the mold compound.

5. An apparatus according to Claim 3, further comprising:

a second integrated circuit die coupled to the second integrated circuit package;

second mold compound in contact with the second integrated circuit die and the second integrated circuit package; and

a third interconnect coupled to the second integrated circuit package,

wherein a first portion of the third interconnect is in contact with the second mold compound, and wherein a second portion of the third interconnect is not in contact with the second mold compound, and wherein a third portion of the third interconnect is in contact with the second integrated circuit package.

6. An apparatus according to Claim 5, further comprising:

a third integrated circuit package;

a fourth interconnect coupled to the third integrated circuit package,

wherein the fourth interconnect is coupled to the third interconnect.

7. An apparatus according to Claim 1, further comprising:

a second integrated circuit die coupled to the integrated circuit die, in contact with the mold compound, and electrically coupled to the integrated circuit package.

8. An apparatus comprising:

an integrated circuit package substrate;

a plurality of integrated circuit die coupled to the integrated circuit package substrate;

mold compound in contact with the plurality of integrated circuit die and the integrated circuit package substrate; and

an interconnect coupled to the integrated circuit package substrate and electrically coupled to one of the plurality of integrated circuit die,

wherein a first portion of the interconnect is in contact with the mold compound, wherein a second portion of the interconnect is not in contact with the mold compound, and wherein a third portion of the interconnect is in contact with the integrated circuit package.

9. An apparatus according to Claim 8, further comprising:

underfill material disposed between the first face of each of the plurality of integrated circuit die and the integrated circuit package substrate.

10. An apparatus according to Claim 8, further comprising:

a second integrated circuit die coupled to the integrated circuit die, in contact with the mold compound, and electrically coupled to the integrated circuit package.

11. A method comprising:

coupling an interconnect to an integrated circuit package;

placing an integrated circuit die on the integrated package; and

placing mold compound on the integrated circuit package and in contact with the integrated circuit die,

wherein a first portion of the interconnect is in contact with the mold compound, wherein a second portion of the interconnect is not in contact with the mold compound, and wherein a third portion of the interconnect is in contact with the integrated circuit package.

12. A method according to Claim 11, wherein placing the mold compound on the integrated circuit package comprises placing the mold compound over the interconnect, and further comprising:

removing mold compound from an upper portion of the interconnect to expose the upper portion.

13. A method according to Claim 11, further comprising:

coupling a second interconnect to the first interconnect, the second interconnect coupled to a second integrated circuit package.

14. A method according to Claim 13, further comprising the second integrated circuit to the mold compound.

15. A system comprising:

an integrated circuit die;

an integrated circuit package coupled to the integrated circuit die;

mold compound in contact with the integrated circuit die and the integrated circuit package; and

an interconnect coupled to the integrated circuit package; and

a double data rate memory electrically coupled to the integrated circuit die,

wherein a first portion of the interconnect is in contact with the mold compound, wherein a second portion of the interconnect is not in contact with the mold compound, and wherein a third portion of the interconnect is in contact with the integrated circuit package.

16. A system according to Claim 15, further comprising:

a second integrated circuit die;

a second integrated circuit package coupled to the second integrated circuit die;

a second interconnect coupled to the second integrated circuit package,

wherein the second interconnect is coupled to the first interconnect.

17. A system according to Claim 16, wherein the second integrated circuit package is coupled to the mold compound.

18. A system according to Claim 15, further comprising:

a second integrated circuit die coupled to the integrated circuit die, in contact with the mold compound, and electrically coupled to the integrated circuit package.

19. A system according to Claim 15, further comprising:

a motherboard electrically coupled to the integrated circuit die and to the memory.